



Docket No.: 050432-0122

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of : Customer Number: 20277
Amit P. MARATHE, et al. : Confirmation Number: 3842
Application No.: 10/811,860 : Group Art Unit: 2811
Filed: March 30, 2004 : Allowed: June 2, 2005
Examiner: Andy Huynh
For: CU INTERCONNECTS WITH COMPOSITE BARRIER LAYERS FOR WAFER-
TO-WAFER UNIFORMITY

LETTER SUBMITTING FORMAL DRAWINGS
AS REPLACEMENT SHEETS


Mail Stop ISSUE FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the Notice of Allowability dated June 2, 2005, submitted herewith is One (1) sheet of Formal Drawings, labeled as Replacement Sheet, in connection with the above referenced application.

Respectfully submitted,

McDERMOTT WILL & EMERY LLP


Arthur J. Steinert
Registration No. 26,106

600 13th Street, N.W.
Washington, DC 20005-3096
Phone: 202.756.8000 AJS:cg
Facsimile: 202.756.8087
Date: August 3, 2005

**Please recognize our Customer No. 20277
as our correspondence address.**